

Patent

Customer No. 31561
Attorney Docket No. 9223-US-PA
Application No.: 10/064,644

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re application of

Applicant : Chi-Hsing Hsu
Application No. : 10/064,644
Filed : August 2, 2002
For : FLIP-CHIP PACKAGE SUBSTRATE AND FLIP-CHIP DIE
Patent No. : 6,710,459 B2
Issue date : March 23, 2004

NOV 22 2005

STATUS INQUIRY-PATENT GRANT

+1-571-273-8300

(Total page: 1)

Attn: Niomi Farmer
Office of Patent Publication
U.S. Patent and Trademark Office
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Dear Ms. Farmer,

We are writing in relation to the above-identified patent which was mailed on April 1, 2004, according to the Patent Application Information Retrieval (PAIR). Nevertheless, we have never received said patent grant so far.

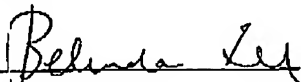
Applicants hereby respectfully request your authority to verify the current status of the above-identified patent. If said patent grant was lost due to an administrative oversight caused by the United States Postal Service (USPS), please kindly reissue the patent certificate at your earliest convenience or let us know if any necessary action should be taken.

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact the undersigned.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

Date: Nov. 22, 2005

By:



Belinda Lee

Registration No.: 46,863

Please send future correspondence to:

7F-1, No. 100, Roosevelt Rd.,

Sec. 2, Taipei 100, Taiwan, R.O.C.

Tel: 886-2-2369 2800 Fax: 886-2-2369 7233 / 886-2-2369 7234

E-MAIL: BELINDA@JCIPGroup.com.tw; USA@JCIPGroup.com.tw